

Title (en)  
SYSTEM AND METHOD FOR AIR COOLING OF PREFORMED MOLDINGS

Title (de)  
SYSTEM UND METHODE ZUR LUFTKÜHLUNG VON VORFORMLINGEN

Title (fr)  
SYSTEME ET PROCÉDÉ DE REFROIDISSEMENT PAR AIR DE PRÉFORMES

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Application  
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Abstract (en)  
[origin: WO0119589A1] The present invention relates to an apparatus and a method of cooling molded preforms. The apparatus and method make advantageous use of air amplifiers to create a flow of cooling air over the molded preforms. In a first embodiment of the present invention, the air amplifiers are mounted to a part removal and cooling robot. In a second embodiment of the present invention, a plurality of air amplifier stations are positioned about an index block to cool the molded preforms. In a third embodiment of the present invention, a vacuuming system is provided to improve the adherence of the air flow created by the air amplifiers to the exterior surfaces of the molded preforms. In a fourth embodiment of the present invention, the air amplifiers are mounted to a movable plate and each amplifier has an internal bore sized to receive a molded preform to be cooled.

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